

PRODUCT CHANGE NOTIFICATION

PCN No.: **PCN211101**

This Product Change Notification serves to inform the Purchaser and Consumer of certain design and or specification changes, described herein, that Crydom will make to its line of Solid State Relay model numbers indicated in the attachment and in accordance with the described time line.

Issue Date: November 22nd 2021

Effective Date: November 24th 2021

Subject:

Temporary Change on Non-Adhesive Thermal Pad

Scope:

Due to the current global pandemic our thermal pad supplier cannot procure the original material used for our thermal pad **HSP-1**. This material is produced by Henkel and they are currently in a global allocation mode, so our supplier proposed an available alternative material to be used. This material has been tested by our Engineering team and they confirmed that the thermal performance is equivalent to the one of the original material.

Description of Changes:

The original material used on this thermal pad is **TCF1000AL**, while the new proposed material is **HF225AC**.

The main differences between the thermal pads made with these 2 materials are as follows:

1. There is a color difference between these 2 materials. The original thermal pad has a gray color while the thermal pad made with the new proposed material is black, as shown in the images below.



Current Thermal Pad



Alternative Thermal Pad

2. The alternative thermal pad has a protective film on both sides, which needs to be removed before installation. Failure to do so will affect the thermal performance, preventing the SSR from properly transferring the dissipated heat.
3. A label will be placed on the bags where the alternative thermal pad will be packaged to clearly indicate the removal of the protective films, as shown below:

Warning: Remove
protective films from
both sides before
installing.

This change will be in effect until further notice since we don't have a clear timeframe of when the supply of the original material will be re-established.



Applicability:

Design/Specification changes described herein apply only to specific models produced as of the effectivity date indicated in the PCN.

Products/Models this PCN applies to:

This notification applies to the following products:

HSP-1
HSP-1-FAR1
HSP-1-RSC1

Stock Returns:

Standard annual stock rotation and warranty provisions per contract apply. There is no need to return stock.

If there are any questions or concerns regarding the changes described in this document please do not hesitate to reach out to us.

A handwritten signature in blue ink, appearing to read "Jesus Miranda", with a long, sweeping flourish extending to the right.

Jesus Miranda
Product Manager
Solid State Relays (Industrial Solutions)
Sensata Technologies